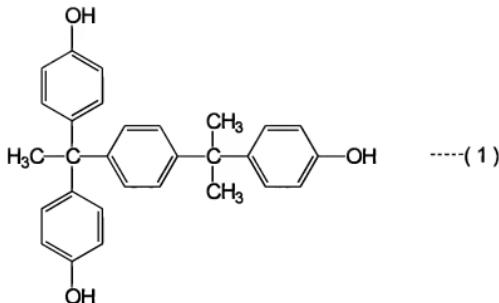


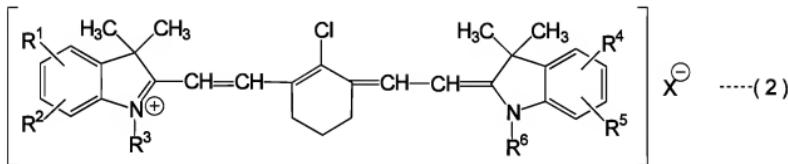
IN THE CLAIMS:

1. (Currently Amended) A positive photosensitive composition comprising:
  - (A) an alkali soluble organic high molecular substance having a phenolic hydroxyl group;
  - (B) a photo-thermal conversion material that absorbs infrared rays from an image exposure light source and converts it to heat;
  - (C) at least one resin selected from the group consisting of: (1) vinylpyrrolidone/vinyl acetate copolymer, (2) vinylpyrrolidone/dimethyl- aminoethyl methacrylate copolymer, (3) vinylpyrrolidone/vinyl caprolactam/ dimethylaminoethyl methacrylate copolymer, (4) polyvinyl acetate, (5) polyvinyl butyral, (6) polyvinyl formal, (7) styrene/maleic acid copolymer, (8) 10 terpene phenol resin, (9) alkylphenol resin, (10) ~~melamine/formaldehyde resin~~; and (11) ketone resin; and
  - (D) a dissolution inhibitor, said alkali soluble organic high molecular substance being in a range from 80 to 95 wt. % of the total solid amount of components (A), (B), (C) and (D), said photo-thermal conversion material being in a range from 0.1 to 10 wt. % of the total solid amount of components (A), (B), (C) and (D), said dissolution inhibitor being in a range from 0.5 to 8 wt. % of the total solid amount of components (A), (B), (C) and (D).

2. (Original) The positive photosensitive composition according to claim 1, wherein the dissolution inhibitor (D) is a compound represented by the following chemical formula (1).



3. (Previously Presented) The positive photosensitive composition according to claim 1, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (2).



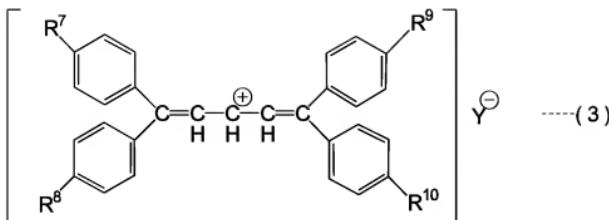
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wherein each of "R<sup>1</sup>" to "R<sup>6</sup>" independently represents a hydrogen atom, an alkyl group having 1 to 3 carbon atoms, or an alkoxy group having 1 to 3 carbon atoms, and "X" represents a halogen atom, ClO<sub>4</sub>, BF<sub>4</sub>, p-CH<sub>3</sub>C<sub>6</sub>H<sub>4</sub>SO<sub>3</sub>, or PF<sub>6</sub>.

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4. (Previously Presented) The positive photosensitive composition according to claim 1, wherein the photo-thermal conversion material (B) is a compound represented by the

following formula (3).



wherein each of "R<sup>7</sup>"~"R<sup>10</sup>" independently represents a hydrogen atom, a methoxyl group,

5 N(CH<sub>3</sub>)<sub>2</sub>, or N(C<sub>2</sub>H<sub>5</sub>)<sub>2</sub>, and "Y" represents C<sub>4</sub>H<sub>9</sub>-B(C<sub>6</sub>H<sub>5</sub>)<sub>3</sub>, p-CH<sub>3</sub>C<sub>6</sub>H<sub>4</sub>SO<sub>3</sub>, or CF<sub>3</sub>SO<sub>3</sub>.

5. (Currently Amended) A photofabrication method comprising:  
providing a positive photosensitive composition, said photosensitive composition  
including:

(A) an alkali soluble organic high molecular substance having a phenolic  
hydroxyl group;

(B) a photo-thermal conversion material that absorbs infrared rays from an  
image exposure light source and converts it to heat;

(C) at least one resin selected from the group consisting of: (1)  
vinylpyrrolidone/vinyl acetate copolymer, (2) vinylpyrrolidone/dimethyl- aminoethyl  
10 methacrylate copolymer, (3) vinylpyrrolidone/vinyl caprolactam/ dimethylaminoethyl  
methacrylate copolymer, (4) polyvinyl acetate, (5) polyvinyl butyral, (6) polyvinyl formal,

(7) styrene/maleic acid copolymer, (8) terpene phenol resin, (9) alkylphenol resin, (10)

melamine/formaldehyde resin, and (11) ketone resin; and

(D) a dissolution inhibitor, said alkali soluble organic high molecular

15 substance being in a range from 80 to 95 wt. % of the total solid amount of components

(A), (B), (C) and (D), said photo-thermal conversion material being in a range from 0.1 to

10 wt. % of the total solid amount of components (A), (B), (C) and (D), said dissolution

inhibitor being in a range from 0.5 to 8 wt. % of the total solid amount of components (A),

(B), (C) and (D);

20 applying the positive photosensitive composition to a subject to be coated;

exposing the positive photosensitive composition as defined in claim 1 to a laser

beam having a wavelength of from 700 to 1,100 nm. to form a positive image without

burning after the applying step.

6. (Previously Presented) The photo fabrication method according to claim 5,  
further comprising the step of applying said photosensitive composition to the production of  
a printing plate, an electronic component [[and]] or a precision equipment component.

7. (Currently Amended) A plate-making method comprising:

providing a positive photosensitive composition, the positive photosensitive  
composition including:

(A) an alkali soluble organic high molecular substance having a phenolic hydroxyl group;

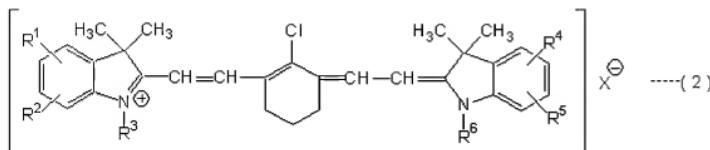
(B) a photo-thermal conversion material that absorbs infrared rays from an image exposure light source and converts it to heat;

(C) at least one resin selected from the group consisting of: (1) vinylpyrrolidone/vinyl acetate copolymer, (2) vinylpyrrolidone/dimethyl- aminoethyl methacrylate copolymer, (3) vinylpyrrolidone/vinyl caprolactam/ dimethylaminoethyl methacrylate copolymer, (4) polyvinyl acetate, (5) polyvinyl butyral, (6) polyvinyl formal, (7) styrene/malic acid copolymer, (8) terpene phenol resin, (9) alkylphenol resin, (10) melamine/formaldehyde resin, and (11) ketone resin; and

(D) a dissolution inhibitor, said alkali soluble organic high molecular substance being in a range from 80 to 95 wt. % of the total solid amount of components (A), (B), (C) and (D), said photo-thermal conversion material being in a range from 0.1 to 10 wt. % of the total solid amount of components (A), (B), (C) and (D), said dissolution inhibitor being in a range from 0.5 to 8 wt. % of the total solid amount of components (A), (B), (C) and (D);

applying the positive photosensitive composition to a subject to be coated;  
exposing the positive photosensitive composition as defined in claim 1 to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image without burning after the applying step.

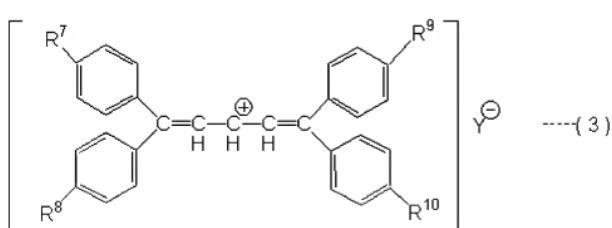
8. (Previously Presented) The positive photosensitive composition according to claim 2, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (2).



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wherein each of “ $\text{R}^1$ ” to “ $\text{R}^6$ ” independently represents a hydrogen atom, an alkyl group having 1 to 3 carbon atoms, or an alkoxy group having 1 to 3 carbon atoms, and “ $\text{X}$ ” represents a halogen atom,  $\text{ClO}_4$ ,  $\text{BF}_4$ ,  $\text{p-CH}_3\text{C}_6\text{H}_4\text{SO}_3$ , or  $\text{PF}_6$ .-----

9. (Previously Presented) The positive photosensitive composition according to claim 2, wherein the photo-thermal conversion material (B) is a compound represented by the following formula (3).



wherein each of "R<sup>7</sup>"~"R<sup>10</sup>" independently represents a hydrogen atom, a methoxyl group, N(CH<sub>3</sub>)<sub>2</sub>, or N(C<sub>2</sub>H<sub>5</sub>)<sub>2</sub>, and "Y" represents C<sub>4</sub>H<sub>9</sub>-B(C<sub>6</sub>H<sub>5</sub>)<sub>3</sub>, p-CH<sub>3</sub>C<sub>6</sub>H<sub>4</sub>SO<sub>3</sub>, or CF<sub>3</sub>SO<sub>3</sub>.

10. (Currently Amended) A photofabrication method comprising:

applying the positive photosensitive composition as defined in claim 2 to a subject to be coated;

exposing the positive photosensitive composition as defined in ~~claim 2~~ to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image without burning after the applying step.

5 11. (Previously Presented) The photofabrication method according to claim 10, further comprising the step of applying said positive photosensitive composition to the production of a printing plate, an electronic component or a precision equipment component.

12. (Currently Amended) A plate-making method comprising:

applying the positive photosensitive composition as defined in claim 2 to a subject to be coated;

exposing the positive photosensitive composition as defined in ~~claim 2~~ to a laser beam having a wavelength of from 700 to 1,100 nm. to form a positive image without burning after the applying step.